Week 1 Assignment 1

The due date for submitting this assignment has passed. As per our records you have not submitted this assignment.

Due on 2019-02-13, 23:59 IST

1) Electronic packaging involves
   a. Packing of electronic products into boxes and cartons
   b. Pricing of the products
   c. Reliable operation of the electronic product
   d. BOM analysis

   No, the answer is incorrect.
   Score: 0
   Accepted Answers:
   c.

2) Which disciplines play a role in electronic packaging industry?
   a. Electrical
   b. Manufacturing
   c. Materials
   d. All of the above

   No, the answer is incorrect.
   Score: 0
   Accepted Answers:
   c.
The Czochralski process is a method of producing
   a. Silicon ingot
   b. Silicon Wafers
   c. Silicon substrates
   d. Silicon dies

- No, the answer is incorrect.
- Score: 0
- Accepted Answers: 
  a. 

4) What are the challenges of IC packaging?
   a. Thermal management
   b. Clock speed
   c. Multi functionality
   d. CPU architecture

- No, the answer is incorrect.
- Score: 0
- Accepted Answers: 
  a. 

5) What is a packaging challenge in smart phones?
   a. Connections from/to imaging CMOS chip
   b. Protection from water spills
   c. Accommodating many components and sub-systems in a small area/volume
   d. All of the above

- No, the answer is incorrect.
- Score: 0
- Accepted Answers: 
  d. 

6) 

- 2 points
Which dopant is used for getting n-type semiconductor?

a. As  
b. Ga  
c. Al  
d. Ge

No, the answer is incorrect.  
Score: 0  
Accepted Answers:

a.

7) What does resistivity of a semiconductor depend on?

a. Length of the device  
b. Mobility of dopant atoms  
c. Number of devices connected in parallel  
d. Atomic weight

No, the answer is incorrect.  
Score: 0  
Accepted Answers:

b.

8) For a p-n junction, current is carried under

a. Reverse Bias  
b. Forward Bias  
c. Zero Bias  
d. None of the above

No, the answer is incorrect.  
Score: 0  
Accepted Answers:

b.
In fabrication of diode, the photolithography process used
   a. Positive photo resist
   b. Negative photo resist
   c. Both
   d. Either can be used

No, the answer is incorrect.
Score: 0
Accepted Answers:
a.

The circuit board in an electronic product
   a. Facilitates communication between different components
   b. Forms a test bed for circuit checks
   c. Both of the above
   d. None of the above

No, the answer is incorrect.
Score: 0
Accepted Answers:
c.